





Applicable standard					
Rating	Operating temperature range	-35°C to +85°C(Note1)	Storage temperature range	-10°C to +60°C(Note3)	
	Operating humidity range	20 % to 80 % (Note2)	Storage humidity range	40 % to 70 %(Note3)	
	Voltage	150 V AC/DC	Current	 AWG 26 : 2.5A    AWG 28 : 2.0A AWG 30 : 1.0A    AWG 32 : 1.0A	
	Applicable connector	DF13-2S-1.25C(##)	Applicable crimp contact	DF13(G)-2630SCF DF13-3032SCF	
<b>Specifications</b>					
Item		Test method	Requirements	QT	AT
<b>Construction</b>					
General examination		Visually and by measuring instrument.	According to drawing.	X	X
Marking		Confirmed visually.		X	X
<b>Electric characteristics</b>					
Contact resistance		100 mA (DC or 1000Hz).	30 mΩ MAX.	X	—
Insulation resistance		100 V DC.	500 MΩ MIN.	X	—
Voltage proof		500 V AC for 1 min.	No flashover or breakdown.	X	—
<b>Mechanical characteristics</b>					
Mechanical operation		30 times insertions and extractions.	① Contact resistance: 30 mΩ MAX. ② No damage, crack or looseness of parts.	X	—
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.	① No electrical discontinuity of 1μs. ② No damage, crack or looseness of parts.	X	—
Shock		490 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 directions.		X	—
<b>Environmental characteristics</b>					
Rapid change of temperature		Temperature -55→ 15 to 35→+85→ 15 to 35 °C Time 30→ 2 to 3→ 30→ 2 to 3 min. Under 5 cycles.	① Contact resistance: 30mΩ MAX. ② Insulation resistance: 500 MΩ MIN. ③ No damage, crack or looseness of parts.	X	—
Damp heat (Steady state)		Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		X	—
Resistance to soldering heat		1) Reflow soldering «Reflow area» 250°C max           10 sec max 230°C min           60 sec max «Preheating area» 170°C to 190°C   60 sec to 120 sec Put through in reflow furnace twice, Leave in ambient temperature and Humidity for 1 hour. 2) Manual soldering Soldering iron temperature :350°C, Soldering time : 3sec. No strength on contact.	No deformation of case of excessive looseness of the terminals.	X	—
Solderability		Soldered at solder temperature, 245°C for insertion duration, 3sec.	Solder shall cover a minimum of 95 % of the surface being immersed.	X	—
<b>Remarks</b> Note 1: Include the temperature rising by current. Note 2: No condensing. Note 3: Apply to the condition of long term storage for unused products before mounted on PCB. After mounted on PCB, operation temperature and humidity range is applied for interim storage during transportation.					
	Count	Description of revisions	Designed	Checked	Date
	1	DIS-H-00004896	HT. SATO	SZ. ONO	20190527
Unless otherwise specified, refer to IEC60512.			Approved	TS. SAKATA	20100128
			Checked	TS. FUKUSHIMA	20100127
			Designed	KT. ISHII	20100127
			Drawn	YK. NAKATSU	20100127
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-083022-21-02
	Specification sheet		Part no.	DF13C-2P-1. 25V (21)	
	Hirose electric co., ltd.		Code no.	CL536-0401-2-21	 1/1